

General Description

The LTP753Q is a 300 mA low dropout regulator that provides voltage with very high accuracy, high stability and low noise. A unique feature that dynamic quiescent current adjustment is employed to have very low current consumption at no-load is integrated in order to enhance the performance for battery operated portable applications. It is available in SOT23-5L, DNF1×1-4L and DFN2×2-6L. Small packages, low noise and low quiescent makes the device to be suitable for space-constrained, noise-sensitive and power-sensitive applications.

Features and Benefits

- Operating Input Voltage Range: 1.7 V to 5.5 V
- Fixed Output Voltage: 0.8V to 3.6V (Contact Factory for Other Voltage Options)
- Low Quiescent Current: 50 μ A Typically
- Soft Start Feature with High Slew Rate Speed
- Low Dropout: 210 mV at 2.8 V Typically, 350 mV at 1.8 V Typically
- Output Voltage Accuracy: $\pm 2\%$ over the specified temperature range
- High Power Supply Ripple Rejection: 70 dB at 1 kHz
- Stable with Ceramic Capacitors 1 μ F
- Built-in Soft Start Circuit
- Over-Current Protection
- Thermal Shutdown Protection
- AEC-Q100 grade 1 applications

Applications

- PDAs, Mobile phones, GPS, Smartphones
- Wireless module
- Portable Equipment
- Other Battery Powered Applications

Table of Content

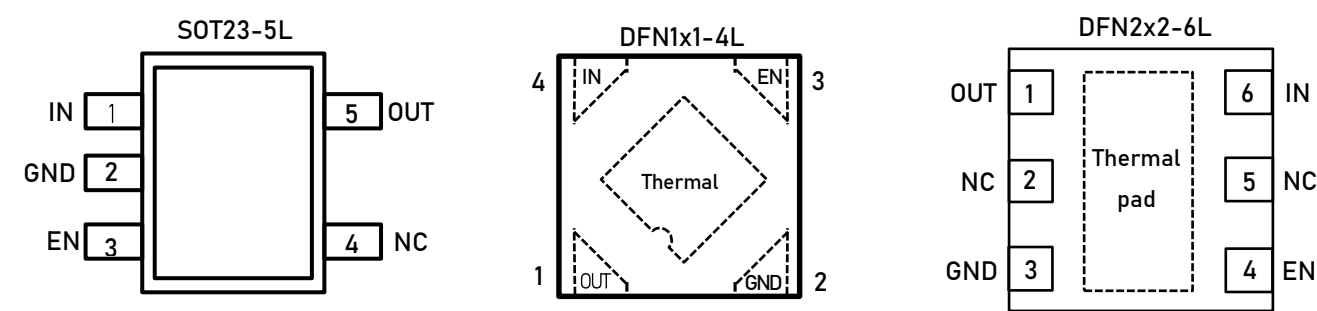
General Description.....	1
Features and Benefits.....	1
Applications.....	1
Table of Content	2
Ordering Information.....	3
Pin Configuration (Top View)	3
Pin Function	3
Block Diagram	4
Application Circuits.....	4
Application Information.....	5
General	5
Input Capacitor	5
Output Capacitor	5
Enable.....	5
Current Limit Protection	5
Thermal Shutdown	5
Power Dissipation and Heat sinking.....	6
Absolute Maximum Ratings	6
ESD Ratings.....	6
Caution.....	7
Recommended Operating Conditions.....	7
Electrical Characteristics	8
Typical Performance Characteristics.....	9
Tape and Reel Information.....	14
Package Dimension	15
Important Notice.....	18

Ordering Information

Model	Package	Ordering Number ^{Note1}	Packing Option
LTP753Q	SOT23-5L	LTP753-xxNQT5	Tape and Reel, 3 000
	DFN1x1-4L	LTP753-xxNQF4	Tape and Reel, 10 000
	DFN2x2-6L	LTP753-xxNQF6	Tape and Reel, 3 000

Note1: xx stands for output voltages, e.g. if xx = 18, the output voltage is 1.8 V; if xx = 30, the output voltage is 3.0 V.

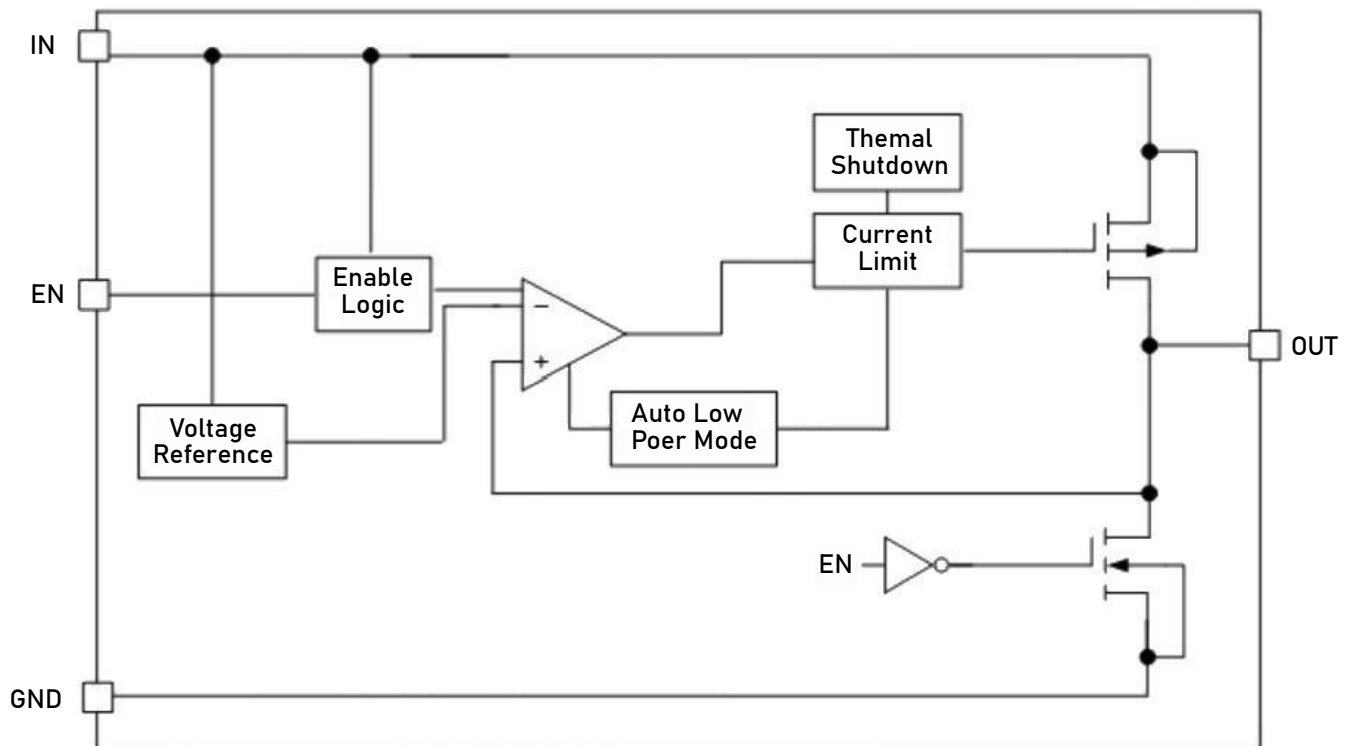
Pin Configuration (Top View)



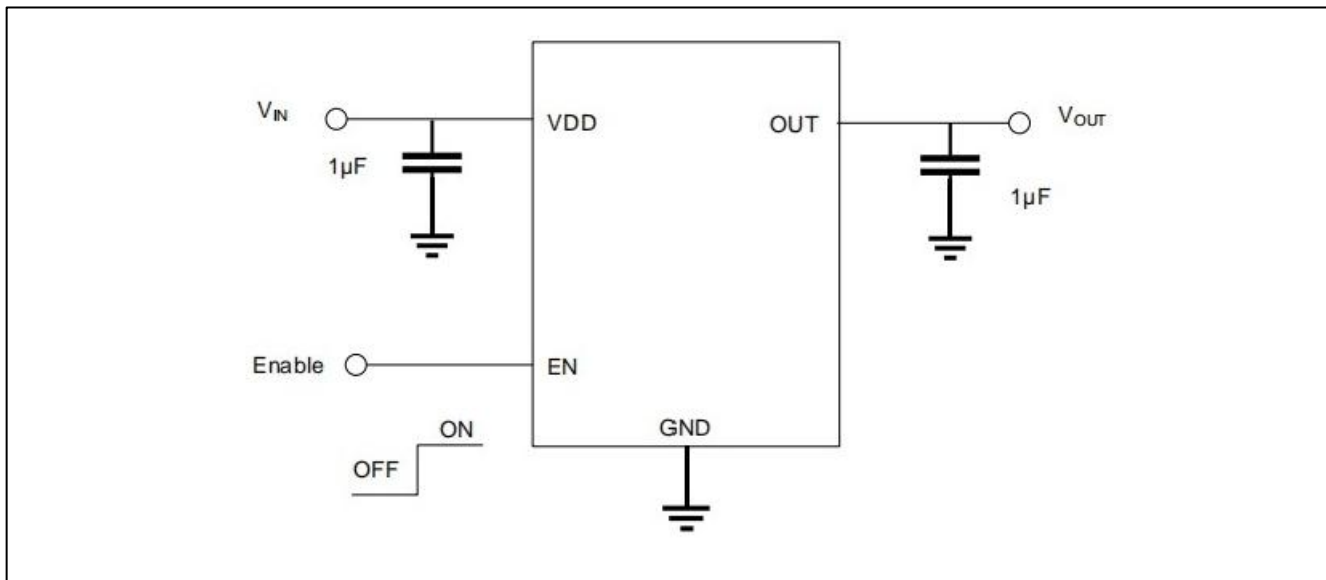
Pin Function

Package			Symbol	Function
SOT23-5L	DFN1x1-4L	DFN2x2-6L		
1	4	6	IN	Power Supply Input Pin.
2	2	3	GND	Ground Pin.
3	3	4	EN	Enable input pin. Drive EN high to enable the device and low to disable it. EN must not be left floating. Tie EN directly to VIN for always-on operation.
4	/	/	NC	No Connection.
5	1	1	OUT	Output Pin
/			EPAD	Exposed pad should be connected directly to the GND pin. Soldered to a large ground copper plane allows for effective heat removal.

Block Diagram



Application Circuits



Note: The EN pin must not be left floating.

Application Information

General

The LTP753Q is a high-performance 300 mA Low Dropout Linear Regulator. Very high PSRR (70 dB at 1 kHz) and excellent dynamic performance as load/line transients provide the device clean and fast transient response despite the unpredictable environment. The unique design to have very low quiescent current makes the device very suitable for various battery powered applications such as tablets, cellular phones, wireless and many other low power-consumption needed situations. Protections in case of output overload, output short circuit condition and overheating are integrated, assuring a very robust design.

Input Capacitor

It is recommended to connect at least a 1 μ F Ceramic X5R or X7R capacitor between IN and GND pins of the device, placed as close as possible to the input pin. This capacitor filters any unwanted AC signals or noises superimposed onto constant Input Voltage. The good input capacitor will limit the influence of input trace inductances and source resistance during sudden load current changes.

Overall line transient response can be improved by using a higher-capacitance and lower Equivalent Series Resistance (ESR) capacitor.

Output Capacitor

The LTP753Q does not require a minimum ESR for the output capacitor but should not be larger than 1.8 ohm. The 1 μ F and X5R or X7R types have low capacitance variations over temperature thus they are recommended. Place the output capacitor as close as possible to the output pin of the regulator.

Enable

The LTP753Q has an EN pin to turn on or turn off the regulator, When the EN pin is in logic high, the regulator will be turned on. The EN pin may be directly tied to V_{IN} to turn on the device. The shutdown current is very close to 0 μ A typically. The Enable input is CMOS logic and cannot be left floating.

Current Limit Protection

When output current at the OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to approximately 460 mA to prevent over-current and to protect the regulator from damage due to overheating.

Thermal Shutdown

When the die temperature exceeds the Thermal Shutdown point (T_{SD} =160 °C typically) the device goes to disabled state and the output voltage is not delivered until the die temperature decreases to 160 °C. The Thermal Shutdown feature provides a protection from a catastrophic device failure at accidental overheating. This protection is not intended to be used as a substitute for proper heat sinking.

Power Dissipation and Heat sinking

The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material and the ambient temperature affect the rate of junction temperature rise for the part. The maximum power dissipation the LTP753Q device can handle is given by:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance. For recommended operating condition specifications the maximum junction temperature is 125°C and T_A is the ambient temperature. The junction to ambient thermal resistance, θ_{JA} , is layout dependent. The maximum power dissipation depends on the operating ambient temperature for fixed $T_{J(MAX)}$ and thermal resistance, θ_{JA} .

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Input Voltage	V_{IN}	-0.3 V to 6 V	V
Output Voltage	V_{OUT}	-0.3 V to $V_{IN} + 0.3$ V or 6 V	V
Enable Voltage	V_{EN}	-0.3 V to 6 V	V
Output Short Circuit Duration	t_{SC}	∞	S
Maximum Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C
Thermal Characteristics, DFN1X1-4L Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	210	°C/W
Thermal Characteristics, DFN2X2-6L Thermal Resistance, Junction-to-Air		75	
Thermal Characteristics, SOT23-5L Thermal Resistance, Junction-to-Air		165	

NOTE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD Ratings

Parameter	Value	Unit
Human Body Model (HBM), per AEC-Q100-002	2 000	V
Charged device model (CDM), per AEC-Q100-011	1 000	V

Caution

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. LINEARIN recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

LINEARIN reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact LINEARIN sales office to get the latest datasheet.

Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Input Voltage	V_{IN}	1.7 to 5.5	V
Output Current	I_{OUT}	0 to 300	mA
Operating Ambient Temperature	T_A	-40 to 125	°C
Effective Input Ceramic Capacitor Value	C_{IN}	1	μF
Effective Output Ceramic Capacitor Value	C_{OUT}	1	μF

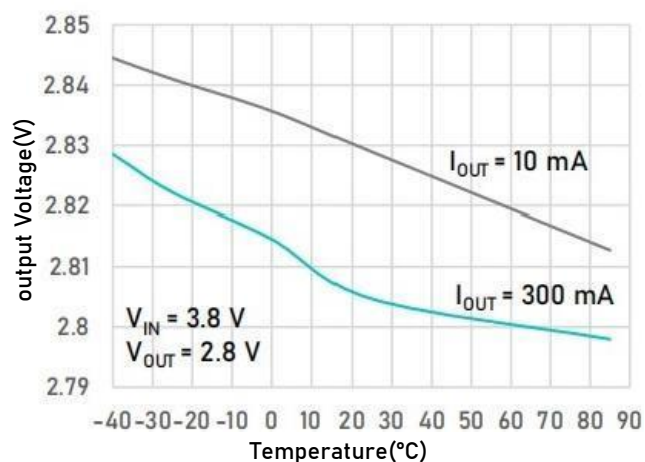
Electrical Characteristics

(V_{IN} = V_{OUT-NOM} +1V, I_{OUT} = 1 mA, T_a = 25°C, C_{IN} = C_{OUT} = 1 µF, unless otherwise noted)

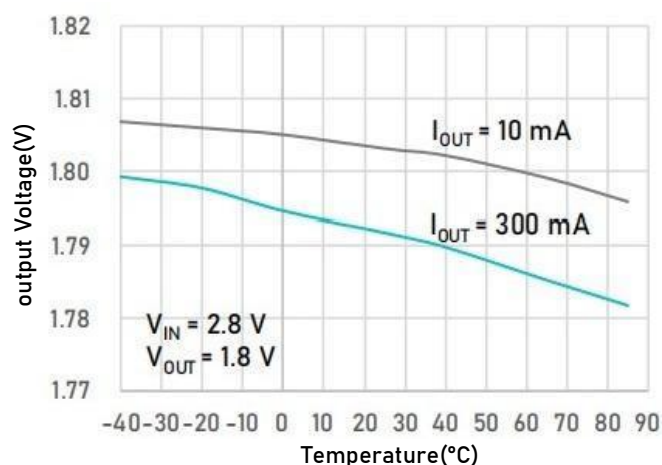
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input Voltage Operation Range	V _{IN}		1.7		5.5	V
Offset voltage Accuracy	V _{OUT}	T _J = -40° C to +85° C, V _{OUT} > 2.0 V	-2		2	%
		T _J = -40° C to +85° C, V _{OUT} ≤ 2.0 V	-40		40	mV
Line Regulation	ΔV _O (ΔV _I)	V _{IN} = V _{OUT-NOM} +0.5 V to 5.5 V V _{IN} ≥ 1.7 V		0.01	0.1	%V _{OUT}
Load Regulation	ΔV _O (ΔI _O)	I _{OUT} = 1 mA to 300 mA (DFN2×2-6L)		20		mV
		I _{OUT} = 1 mA to 300 mA (DFN1×1-4L)		25		
Dropout Voltage	V _{DO}	I _{OUT} = 300 mA, V _{OUT} = 2.8 V		210		mV
		I _{OUT} = 300 mA, V _{OUT} = 1.8 V		350		
Output Current Limit	I _{LIM}	V _{OUT} = 90%V _{OUT-NOM}		460		mA
Quiescent Current	I _Q	I _{OUT} = 0 mA		50	95	µA
Shutdown Current	I _{SHDN}	V _{EN} ≤ 0.4 V, V _{IN} = 5.5 V		0.01	1	µA
EN Threshold	V _{EN-TH}	V _{EN} rising	0.9			V
EN Hysteresis	V _{EN-HY}	V _{EN} falling			0.2	V
Output Voltage Slew Rate	V _{OUT_SR}	I _{OUT} = 10 mA		170		mV/µs
EN Pin Input Current	I _{EN}	V _{EN} = 5.5 V		0.3		µA
Power Supply Rejection Ratio	PSRR	V _{OUT} = 2.8 V, I _{OUT} = 10 mA, f=1kHz		70		dB
Output Voltage Noise	V _N	f = 10 Hz to 100 kHz		75		µV _{RMS}
Thermal Shutdown Temperature	T _{SD}	Temperature rising from T _J = +25°C		160		°C
Thermal Shutdown Hysteresis	T _{SDH}	Temperature falling from T _{SD}		20		°C
Active Output Discharge Resistance	R _{DIS}	V _{EN} < 0.4 V		100		Ω

Typical Performance Characteristics

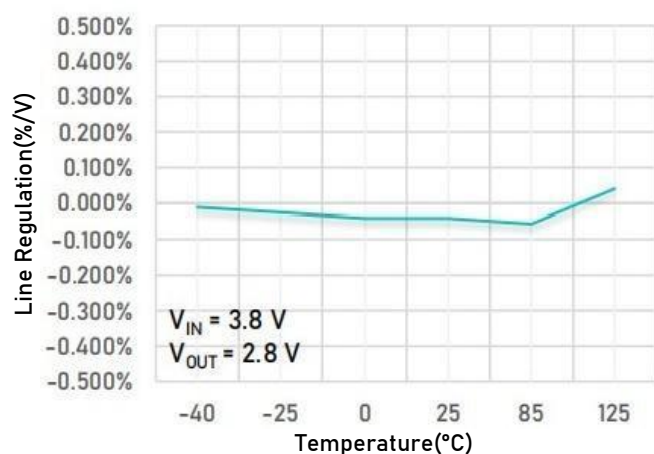
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.



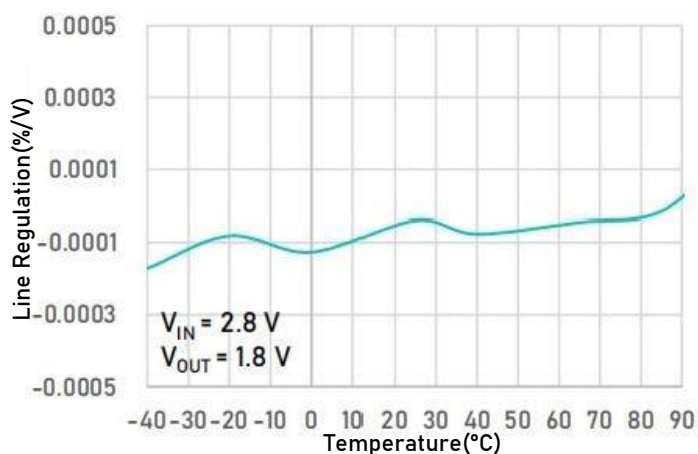
Output Voltage vs. Temperature

 $V_{OUT} = 2.8\text{ V}$ DFN1x1-4L

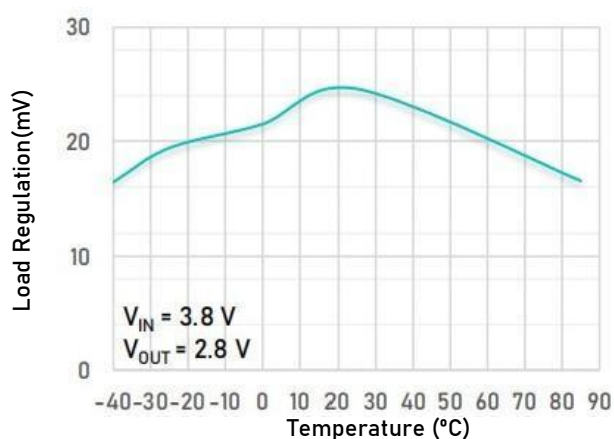
Output Voltage vs. Temperature

 $V_{OUT} = 1.8\text{ V}$ DFN2x2-6L

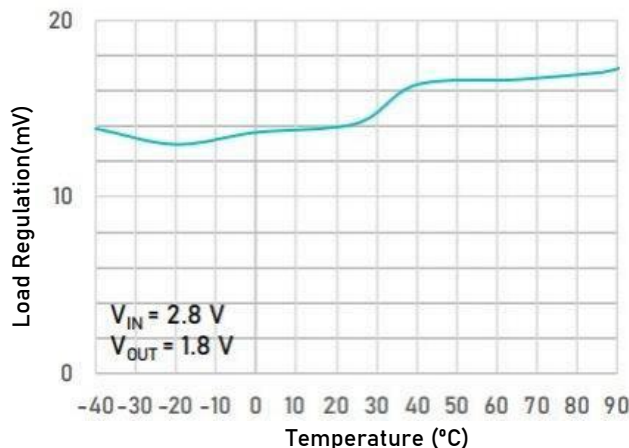
Line Regulation vs. Temperature

 $V_{OUT} = 2.8\text{ V}$ DFN1x1-4L

Line Regulation vs. Temperature

 $V_{OUT} = 1.8\text{ V}$ DFN2x2-6L

Load Regulation vs. Temperature

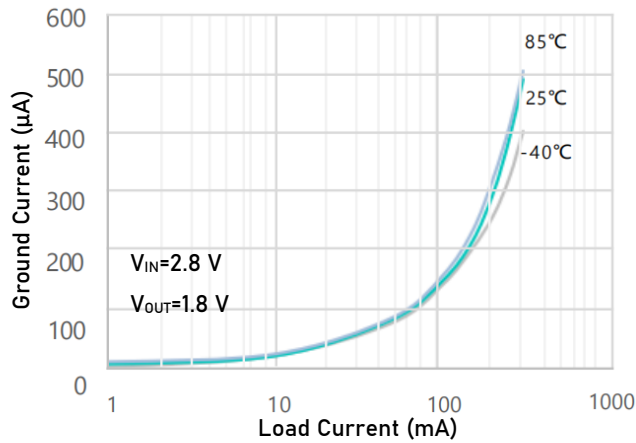
 $V_{OUT} = 2.8\text{ V}$ DFN1x1-4L

Load Regulation vs. Temperature

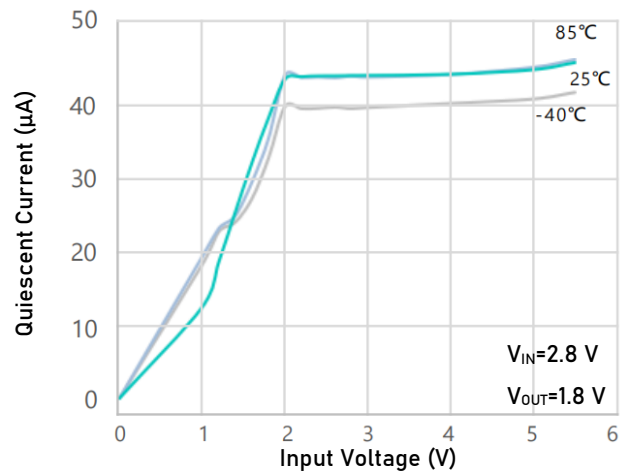
 $V_{OUT} = 1.8\text{ V}$ DFN2x2-6L

Typical Performance Characteristics (Cont.)

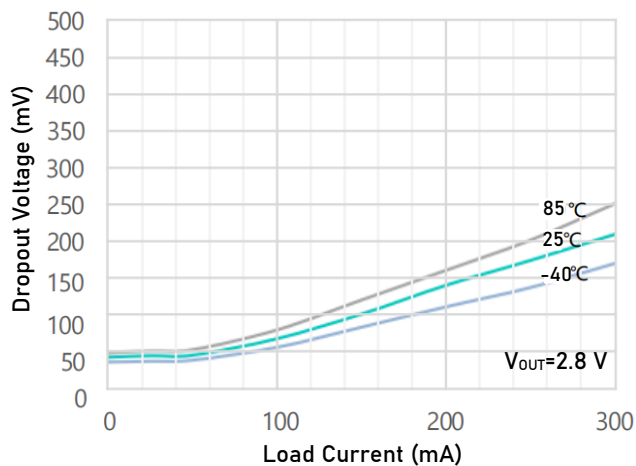
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.



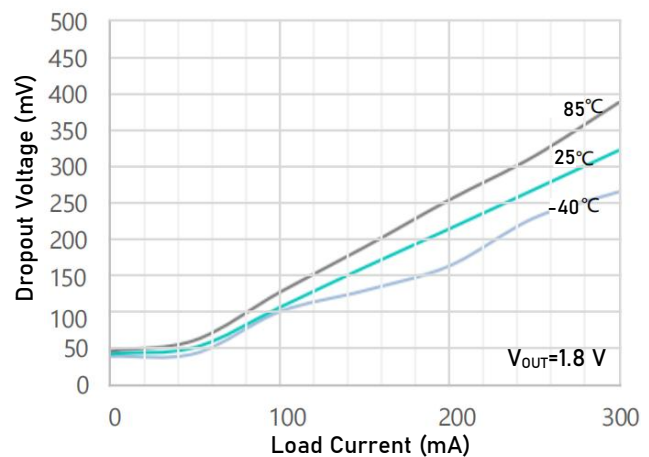
Ground Current vs. Load Current
 $V_{OUT} = 1.8 \text{ V DFN2} \times 2\text{-}6\text{L}$



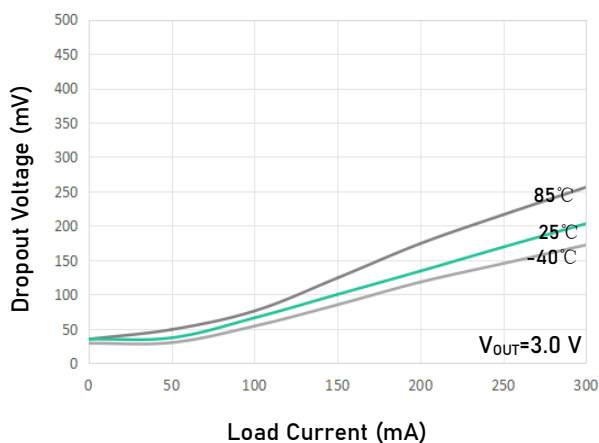
Quiescent Current vs. Input Voltage
 $V_{OUT} = 1.8 \text{ V DFN2} \times 2\text{-}6\text{L}$



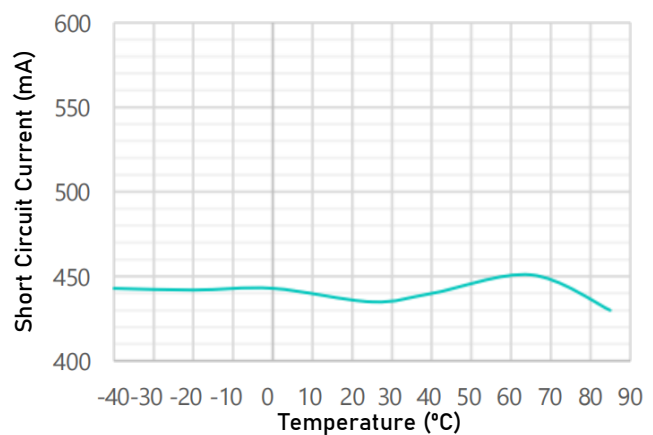
Dropout Voltage vs. Load Current
 $V_{OUT} = 2.8 \text{ V DFN1} \times 1\text{-}4\text{L}$



Dropout Voltage vs. Load Current
 $V_{OUT} = 1.8 \text{ V DFN2} \times 2\text{-}6\text{L}$



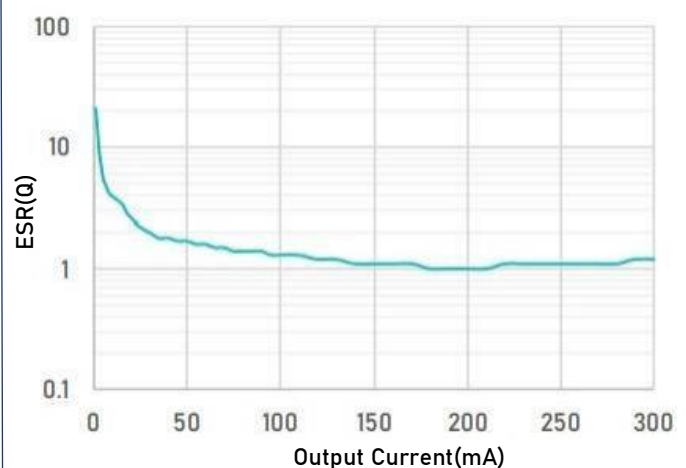
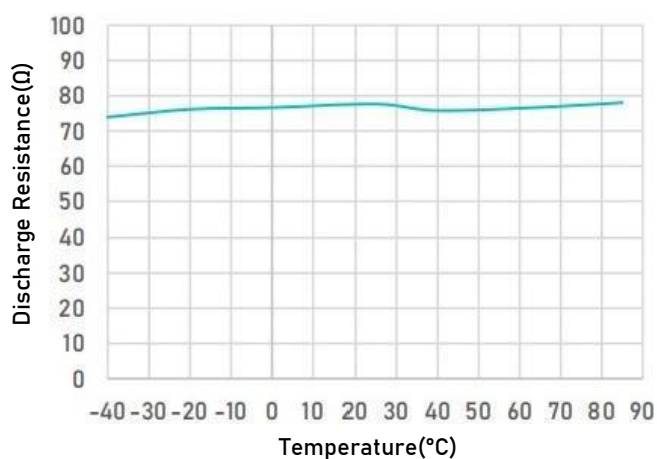
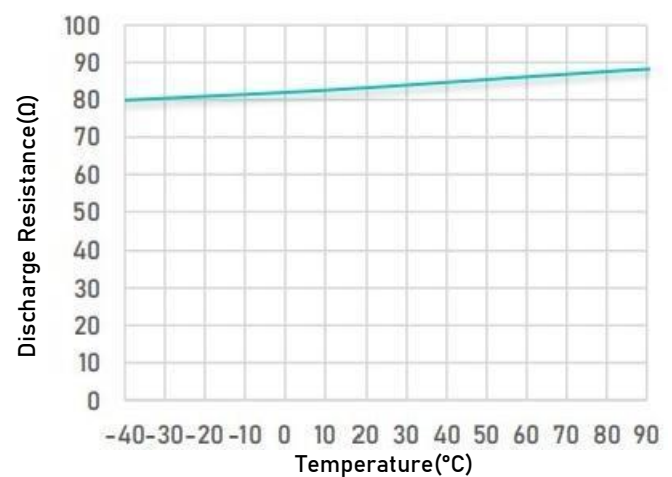
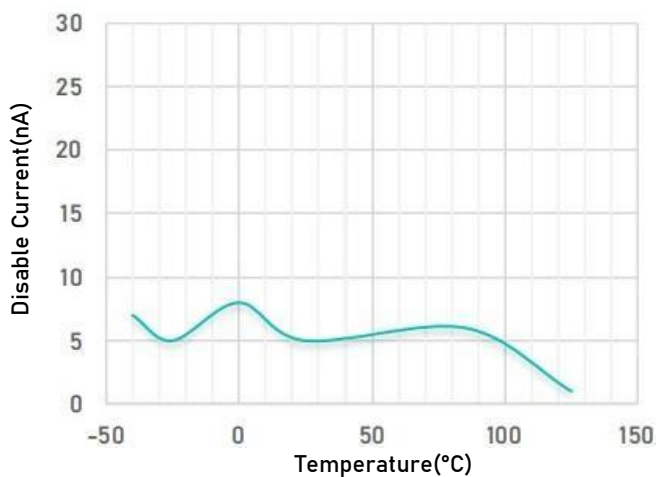
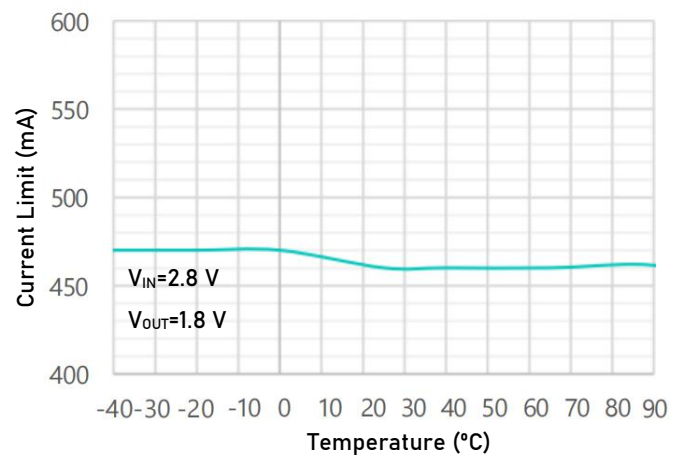
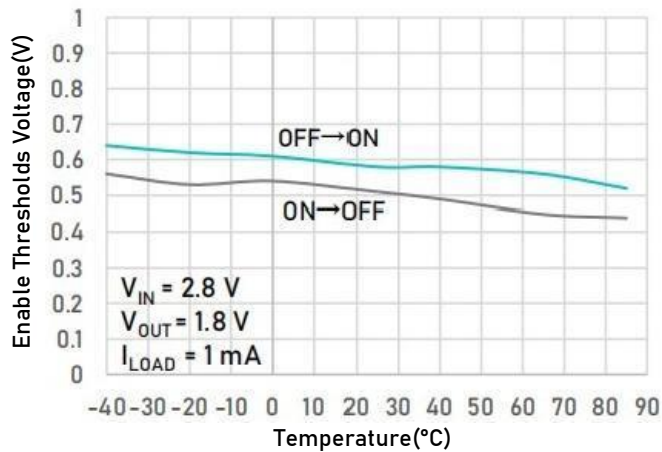
Dropout Voltage vs. Load Current
 $V_{OUT} = 3.0 \text{ V DFN1} \times 1\text{-}4\text{L}$



Short Circuit Current vs. Temperature
 $V_{OUT} = 1.8 \text{ V DFN2} \times 2\text{-}6\text{L}$

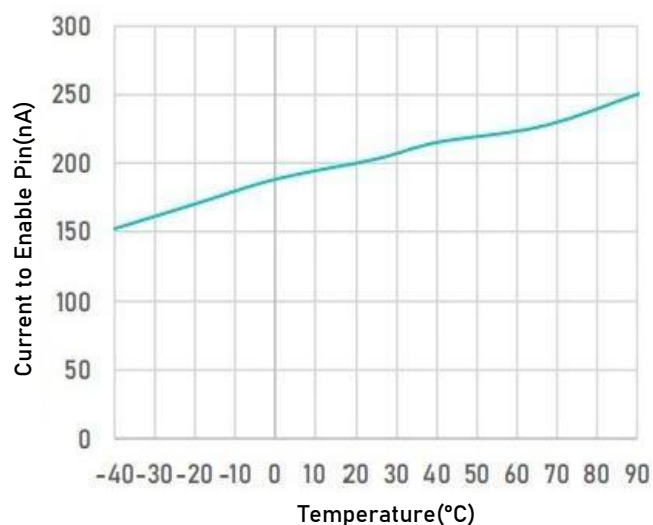
Typical Performance Characteristics (Cont.)

Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

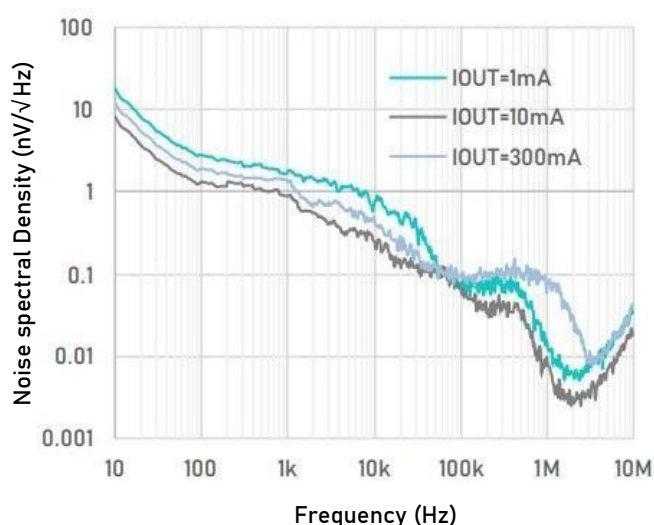


Typical Performance Characteristics (Cont.)

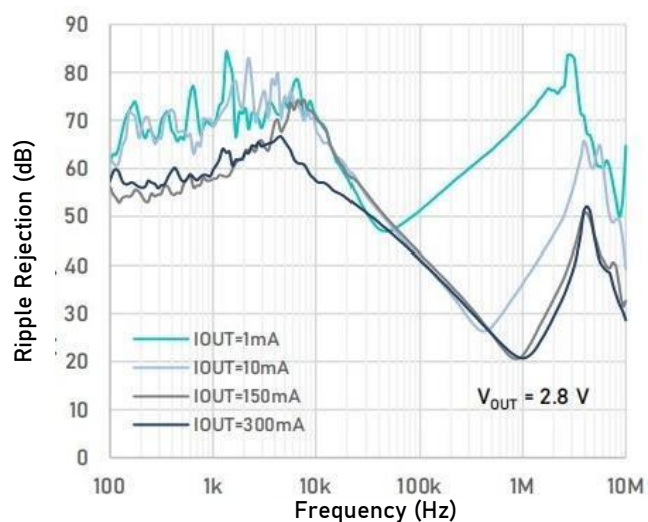
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.



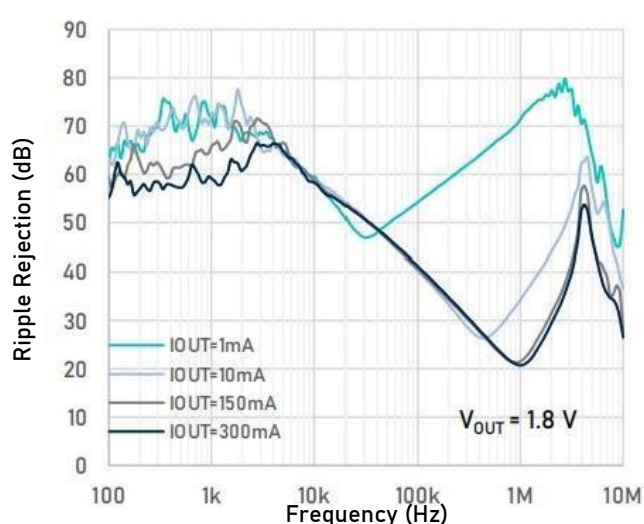
Current to Enable Pin vs. Temperature



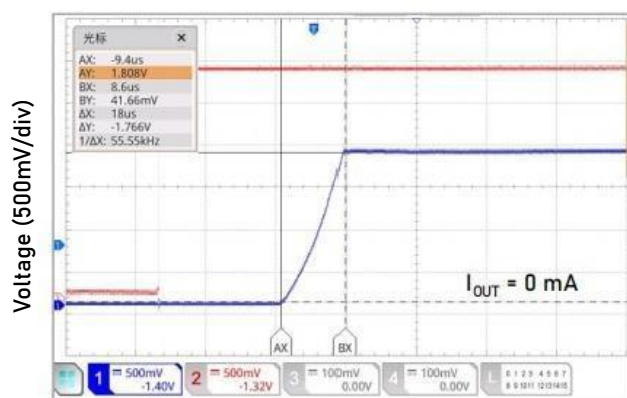
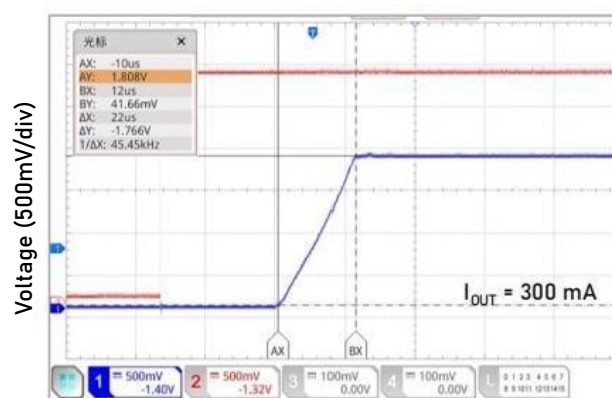
Output Voltage Noise Spectral Density vs. Frequency



Power Supply Rejection Ratio vs. Frequency

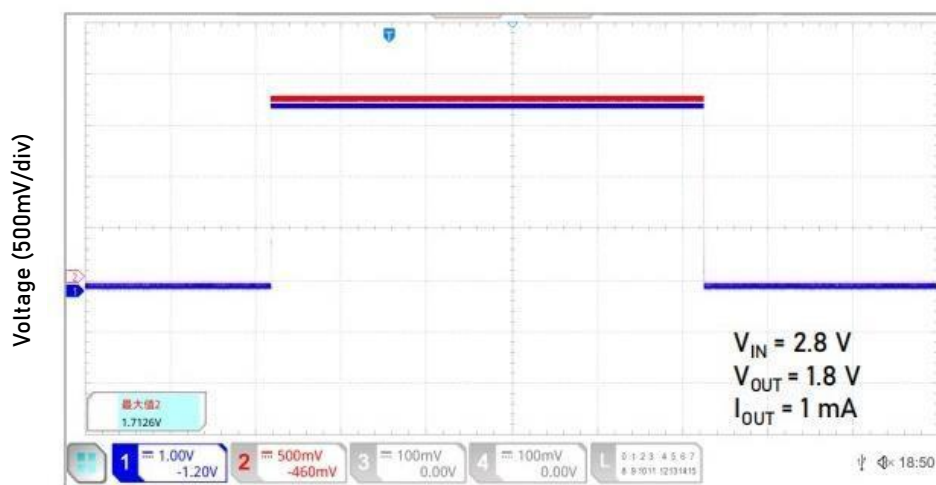


Power Supply Rejection Ratio vs. Frequency

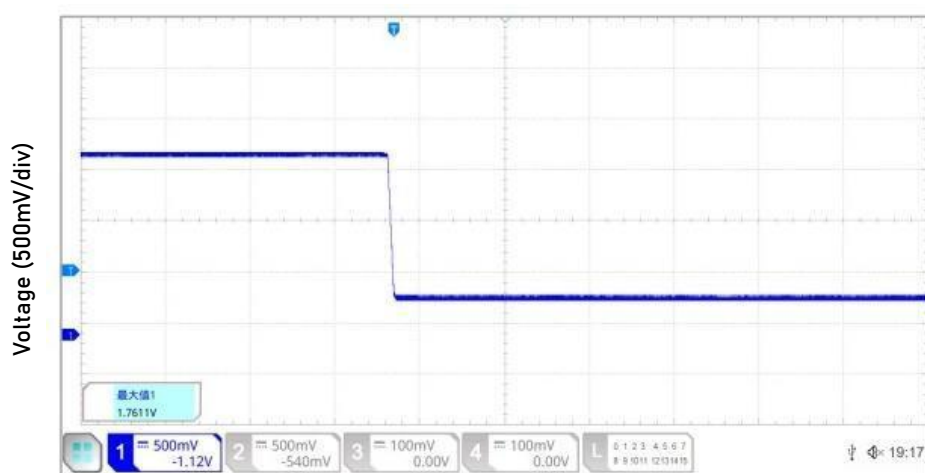
 V_{OUT} Slew-Rate - $I_{OUT}=0\text{mA}$  V_{OUT} Slew-Rate - $I_{OUT}=300\text{mA}$

Typical Performance Characteristics (Cont.)

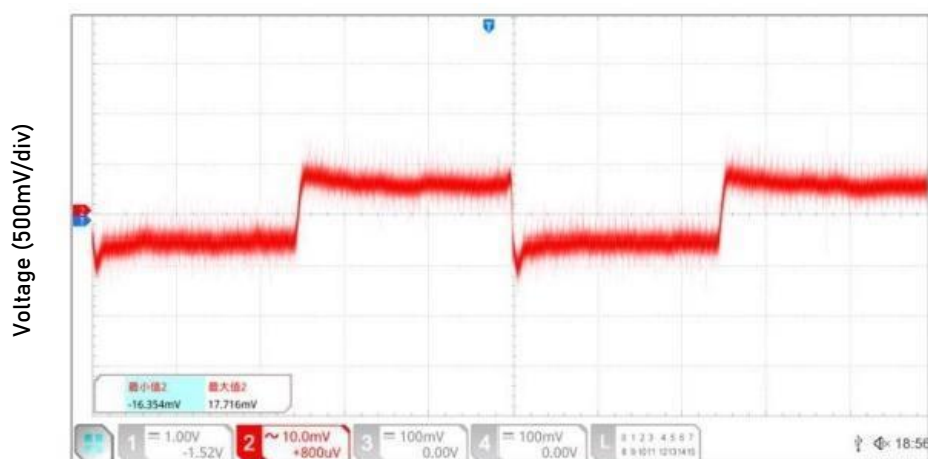
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.



Time (50μS/div)
Turn-on/off-Slow Rising



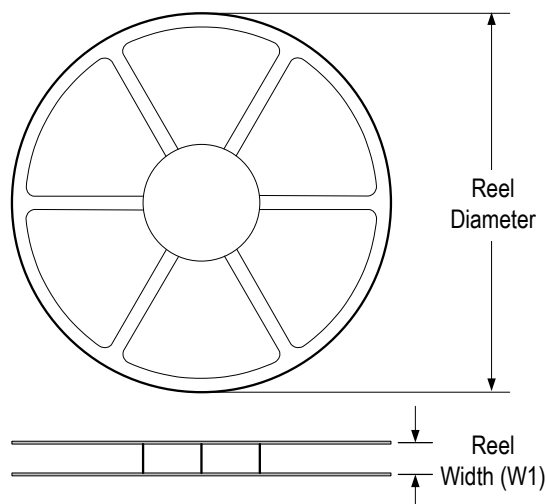
Time (50μS/div)
Overheating Protection



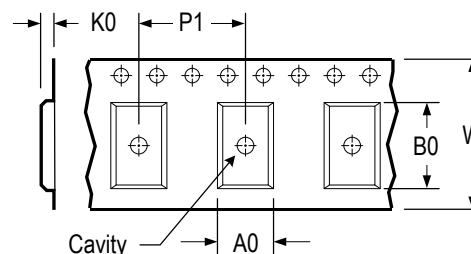
Time (50μS/div)
Load Transient Response -I_{OUT}=1 to 300mA

Tape and Reel Information

REEL DIMENSIONS

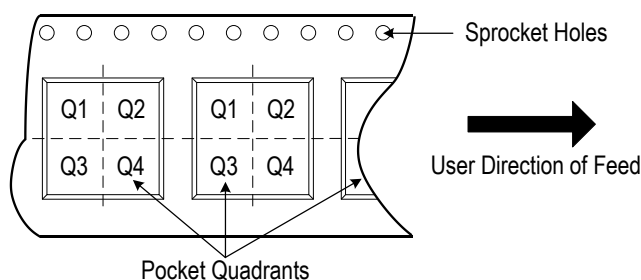


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

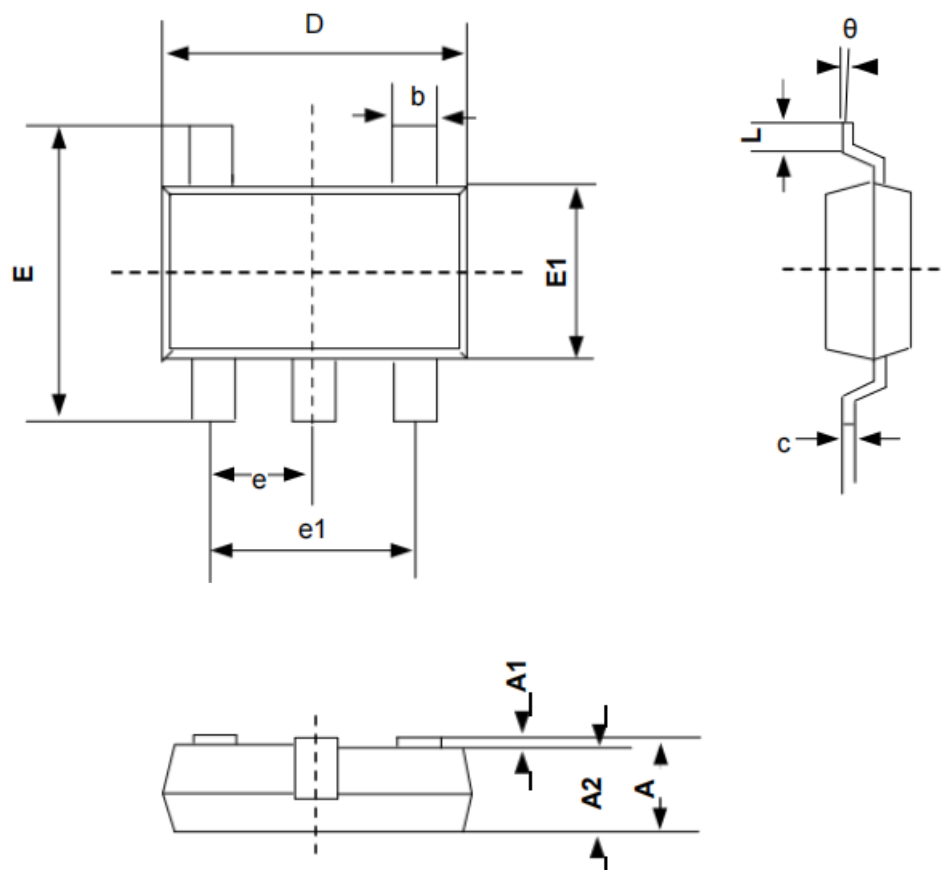


* All dimensions are nominal

Device	Package Type	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin 1 Quadrant
LTP753-xxNQT5	SOT23	5	3 000	178	9.5	3.3	3.2	1.5	4.0	8.0	Q3
LTP753-xxNQF4	DFN1x1	4	10 000	178	9.5	1.1	1.1	0.5	2.0	8.0	Q1
LTP753-xxNQF6	DFN2x2	6	3 000	178	9.5	2.2	2.2	1.0	4.0	8.0	Q1

Package Dimension

SOT23-5L

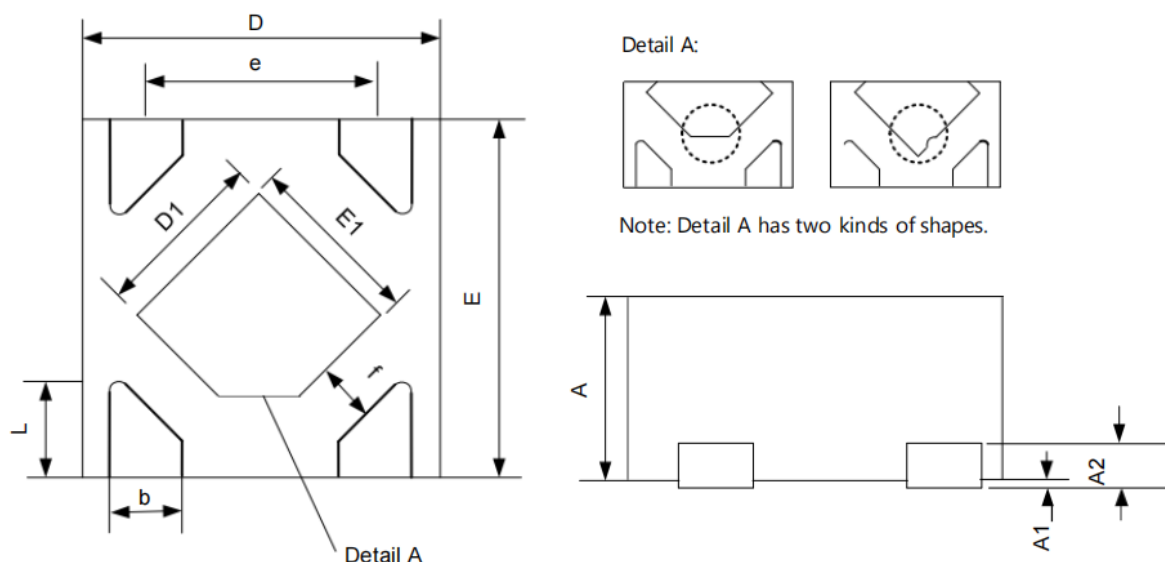


Unit: mm

Symbol	Dimensions In Millimeters	
	MIN	MAX
A	0.700	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.350	0.500
c	0.080	0.200
D	2.820	3.020
E	2.650	2.950
E1	1.600	1.700
e	0.950BSC	
e1	1.800	2.000
L	0.300	0.600
Θ	0°	8°

Package Dimension (Cont.)

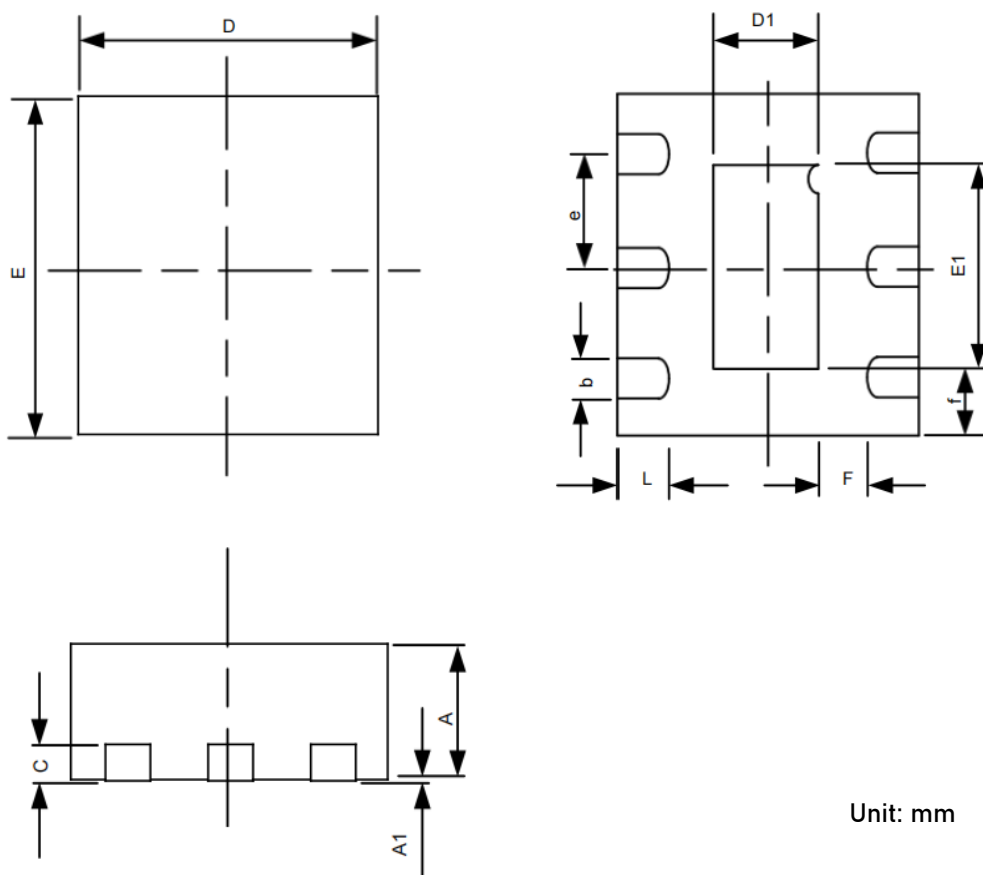
DFN1x1-4L



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.340	0.370	0.400
A1	0.000	0.020	0.050
A2	0.100REF		
D	0.950	1.000	1.050
D1	0.430	0.480	0.530
E	0.950	1.000	1.050
E1	0.430	0.480	0.530
b	0.170	0.220	0.270
e	0.650BSC		
f	0.190	0.195	0.200
L	0.200	0.250	0.300

Package Dimension (Cont.)

DFN2x2-6L



Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.700	0.750	0.800
A1	0.000	0.020	0.050
b	0.225	0.250	0.275
c	0.190	0.210	0.230
D	1.900	2.000	2.100
E	1.900	2.000	2.100
E1	1.150	1.200	1.250
D1	0.650	0.700	0.750
e	0.625	0.650	0.675
L	0.300	0.350	0.400
R	0.100		
F	0.280	0.300	0.320
f	0.380	0.400	0.420

Important Notice

Linearin is a global fabless semiconductor company specializing in advanced high-performance high-quality analog/mixed-signal IC products and sensor solutions. The company is devoted to the innovation of high performance, analog-intensive sensor front-end products and modular sensor solutions, applied in multi-market of medical & wearable devices, smart home, sensing of IoT, intelligent industrial & smart factory (industrial 4.0), and automobiles. Linearin's product families include widely-used standard catalog products, solution-based application specific standard products (ASSPs) and sensor modules that help customers achieve faster time-to-market products. Go to <http://www.linearin.com> for a complete list of Linearin product families.

For additional product information, or full data sheet, please contact with the Linearin's Sales Department or Representatives.